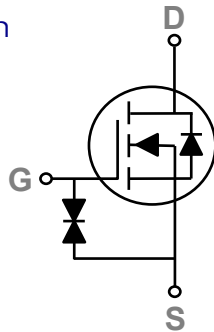
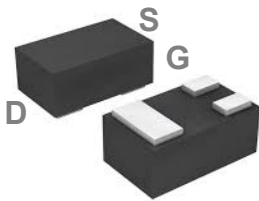


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOT883 Pin Configuration



BVDSS	RDSON	ID
20V	350mΩ	500mA

### Features

- 20V,500mA,  $R_{DS(ON)} = 350m\Omega @ V_{GS} = 4.5V$
- Worldwide Smallest Package : 1x0.6x0.45 mm
- Fast switching
- Green Device Available
- Suit for 1.2V Gate Drive Applications
- 2KV HBM ESD Capability

### Applications

- Notebook
- Smartphone
- Battery Protection
- Hand-held Instruments

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 8$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	500	mA
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	320	mA
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	1000	mA
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	155	mW
	Power Dissipation – Derate above $25^\circ\text{C}$	1.25	mW/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	800	$^\circ\text{C/W}$

**Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25\text{ }^\circ\text{C}$ , $I_D=1mA$	---	-0.01	---	$V/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=20V, V_{GS}=0V, T_J=25\text{ }^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=16V, V_{GS}=0V, T_J=125\text{ }^\circ\text{C}$	---	---	10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 8V, V_{DS}=0V$	---	---	$\pm 20$	$\mu A$

**On Characteristics**

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=4.5V, I_D=0.5A$	---	200	350	m $\Omega$
		$V_{GS}=2.5V, I_D=0.4A$	---	235	450	
		$V_{GS}=1.8V, I_D=0.2A$	---	295	600	
		$V_{GS}=1.5V, I_D=0.1A$	---	365	800	
		$V_{GS}=1.2V, I_D=0.1A$	---	600	1500	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	0.3	0.5	0.8	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	3	---	$mV/^\circ\text{C}$

**Dynamic and switching Characteristics**

$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=10V, V_{GS}=4.5V, I_D=0.5A$	---	1	2	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	0.26	0.5	
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	0.2	0.4	
$T_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{DD}=10V, V_{GS}=4.5V, R_G=10\Omega, I_D=0.5A$	---	5	10	ns
$T_r$	Rise Time <sup>2,3</sup>		---	3.5	7	
$T_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	14	28	
$T_f$	Fall Time <sup>2,3</sup>		---	6	12	
$C_{iss}$	Input Capacitance	$V_{DS}=10V, V_{GS}=0V, F=1MHz$	---	38.2	75	pF
$C_{oss}$	Output Capacitance		---	14.4	28	
$C_{riss}$	Reverse Transfer Capacitance		---	6	12	

**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	500	mA
$I_{SM}$	Pulsed Source Current		---	---	1000	mA
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=0.2A, T_J=25\text{ }^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

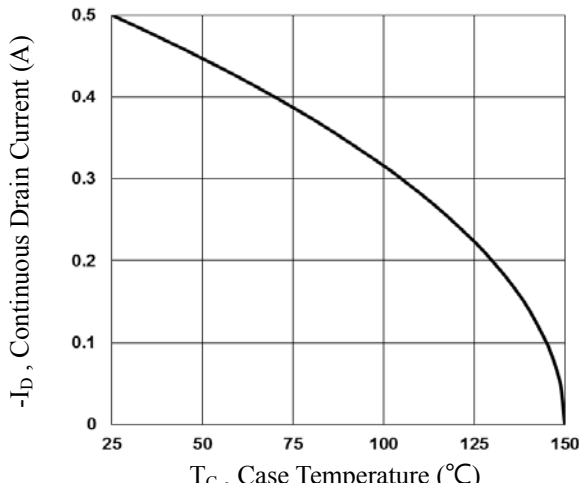


Fig.1 Continuous Drain Current vs.  $T_c$

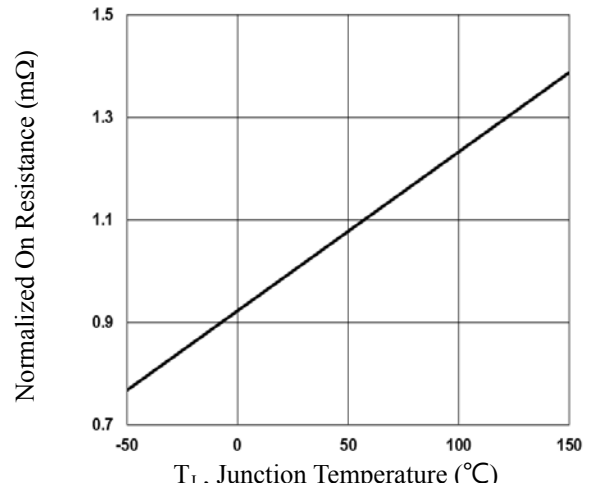


Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$

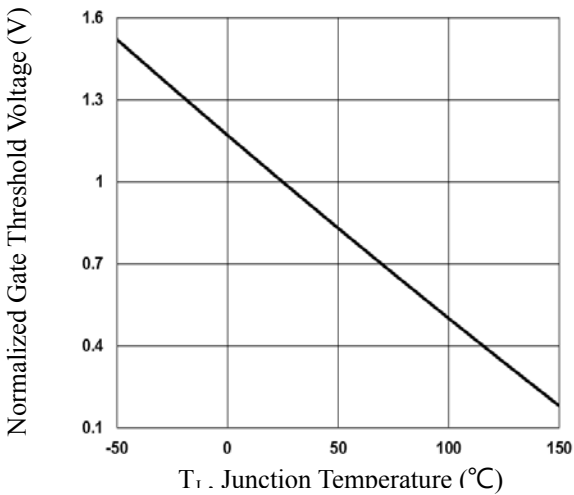


Fig.3 Normalized  $V_{th}$  vs.  $T_j$

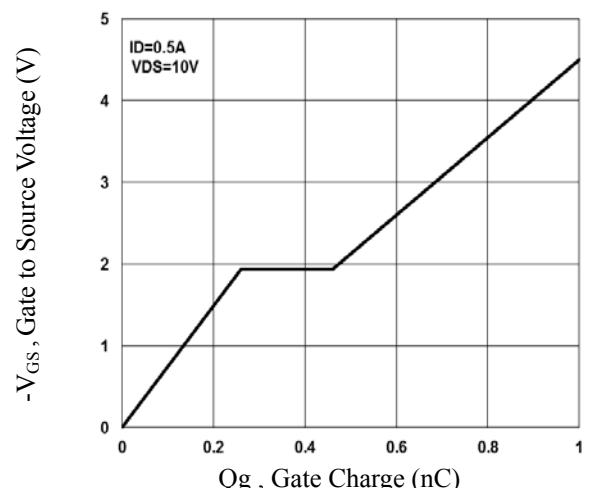


Fig.4 Gate Charge Waveform

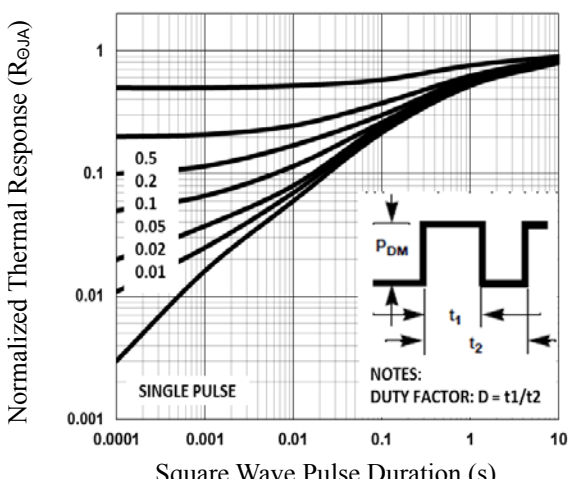


Fig.5 Normalized Transient Response

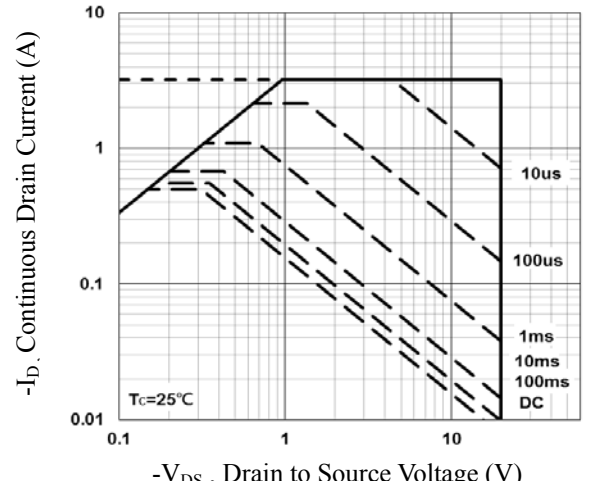


Fig.6 Maximum Safe Operation Area

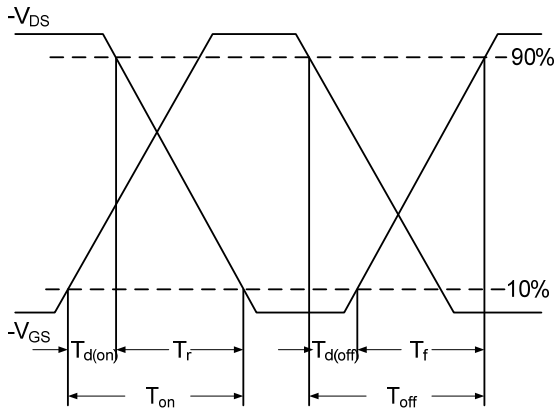


Fig.7 Switching Time Waveform

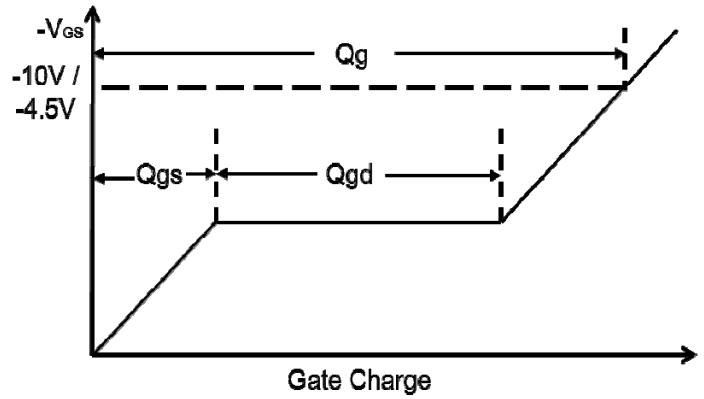
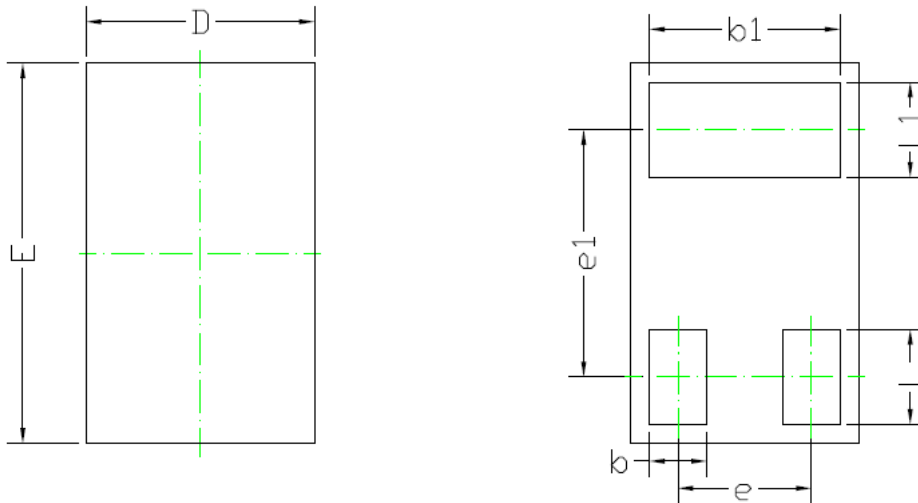
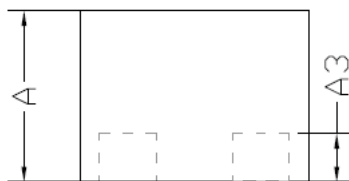


Fig.8 Gate Charge Waveform

### SOT883 PACKAGE INFORMATION



SIDE VIEW



SYMBOL	COMMON DIMENSIONS MILLIMETER		
	MIN	NOM.	MAX
	A	0.40	0.45
A3	0.127 BSC		
D	0.55	0.60	0.65
E	0.95	1.00	1.05
e	0.35 BSC		
e1	0.65 BSC		
b	0.13	0.15	0.18
b1	0.45	0.50	0.55
L	0.20	0.25	0.30
L1	0.20	0.25	0.30